

APPROVED	O.G. FIG.
BY	CLASS SUBCLASS
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NAGAMIMA et al.; Appln. No. 09/941,744; Filed 3/30/01
"Semiconductor Device"

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FIG. 1A
RELATED ART

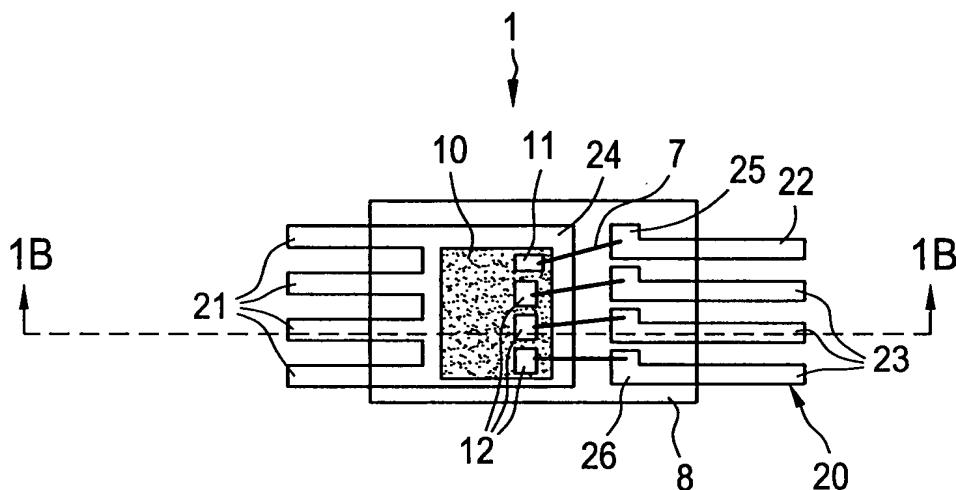
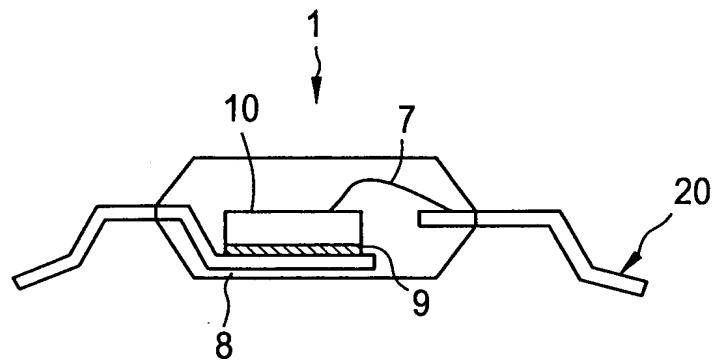


FIG. 1B
RELATED ART



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FIG. 2A
RELATED ART

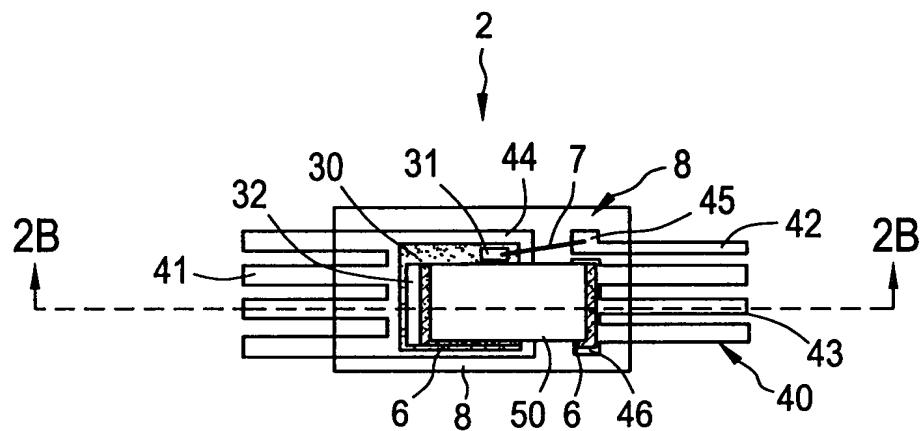
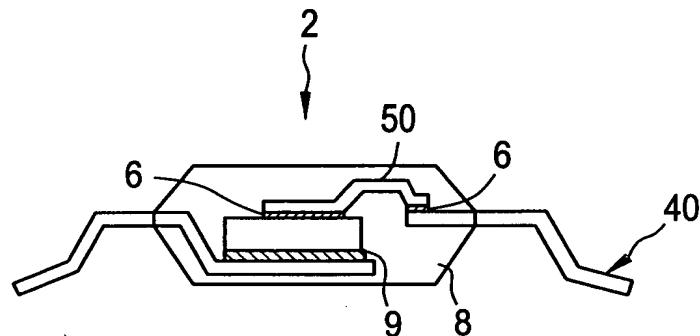


FIG. 2B
RELATED ART



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FIG. 3A

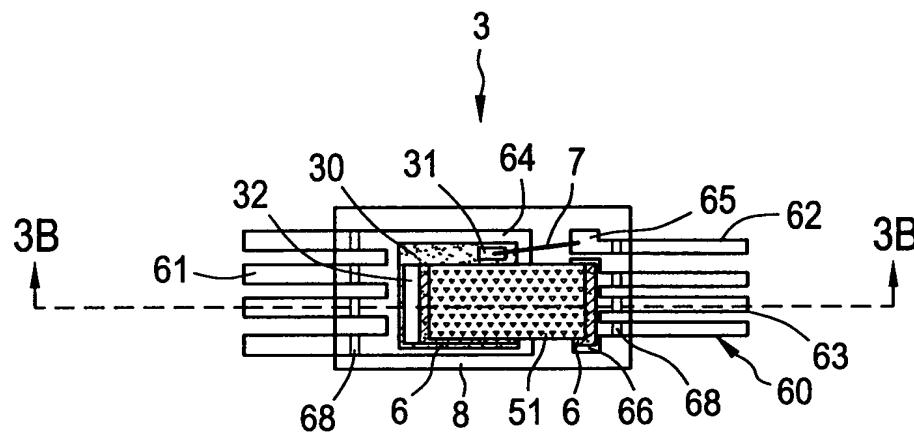
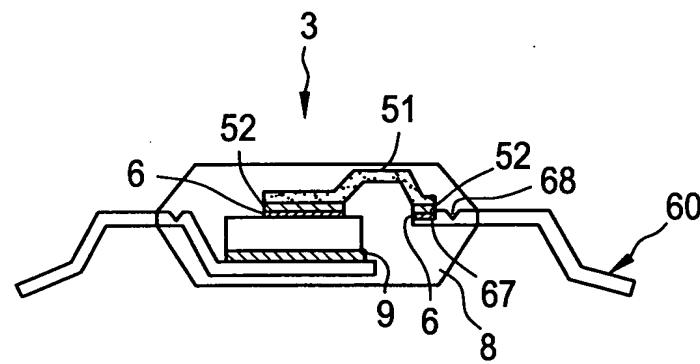


FIG. 3B



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FIG. 4A

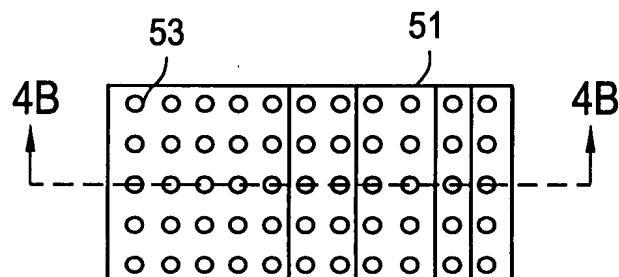


FIG. 4B

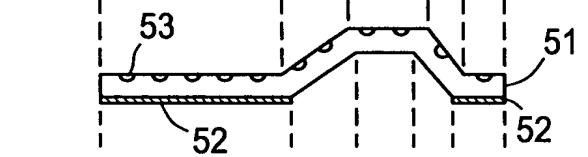
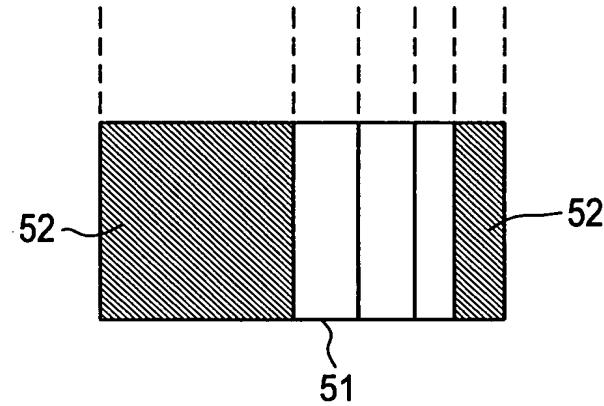


FIG. 4C



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FIG. 5A

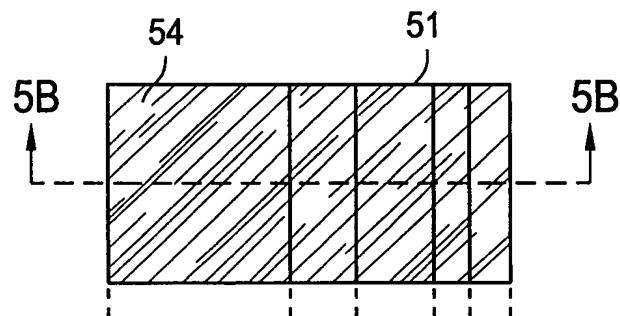


FIG. 5B

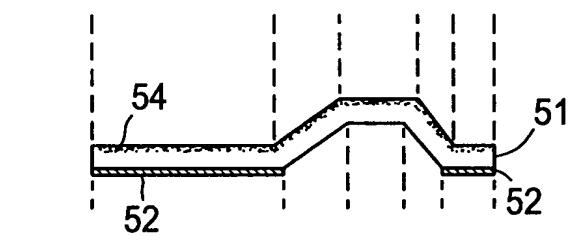
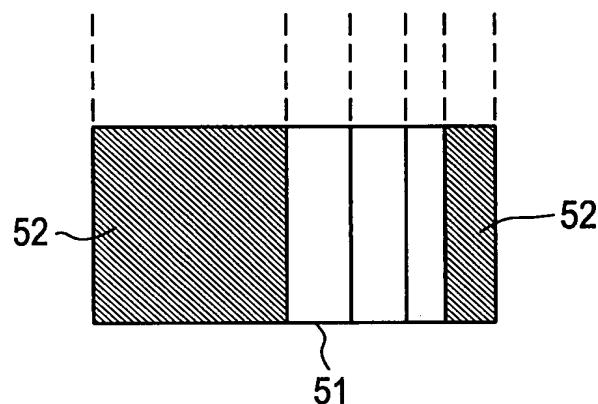


FIG. 5C



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FIG. 6A

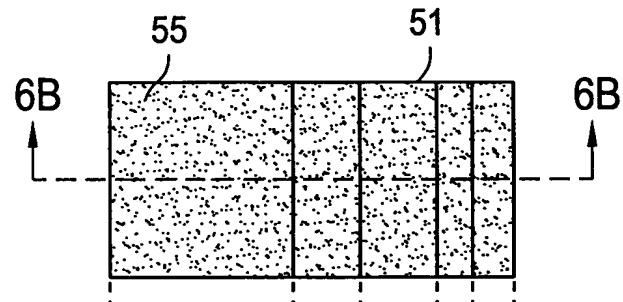


FIG. 6B

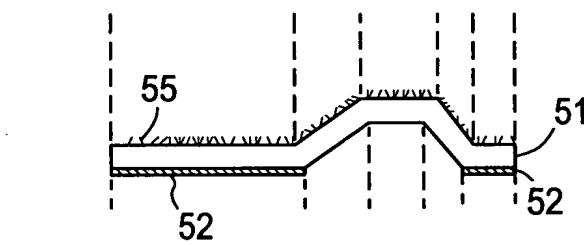
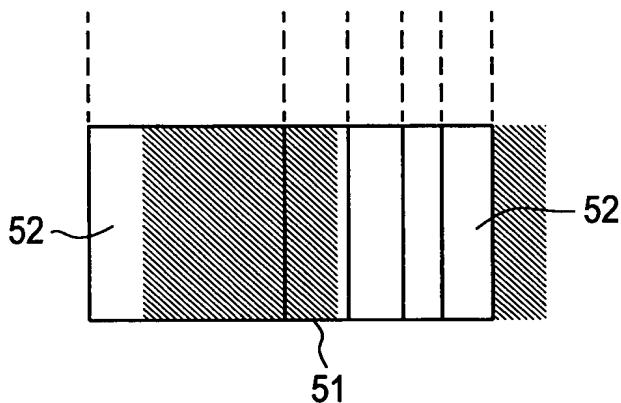


FIG. 6C



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FIG. 7A

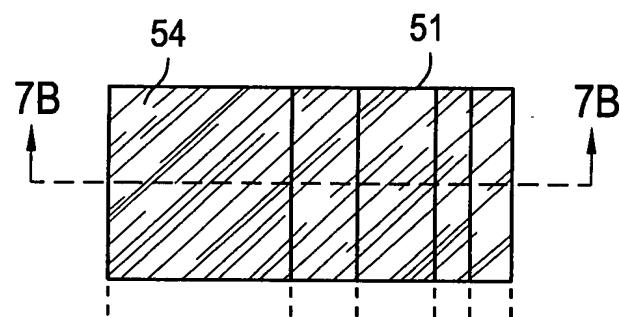


FIG. 7B

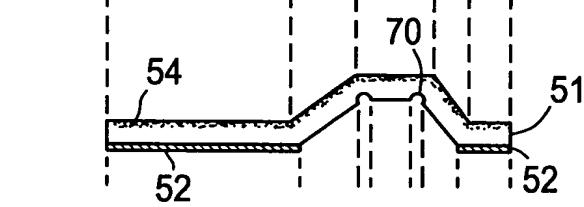
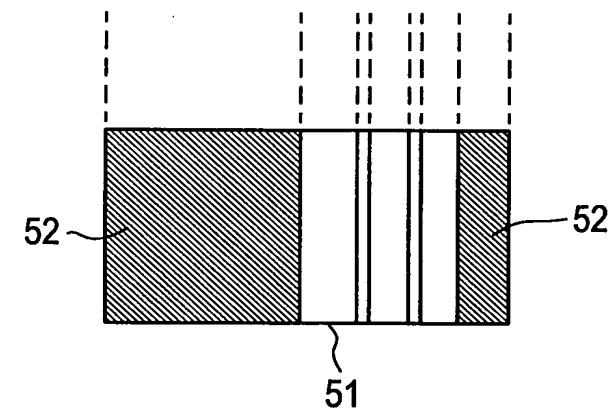


FIG. 7C



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FIG. 8A

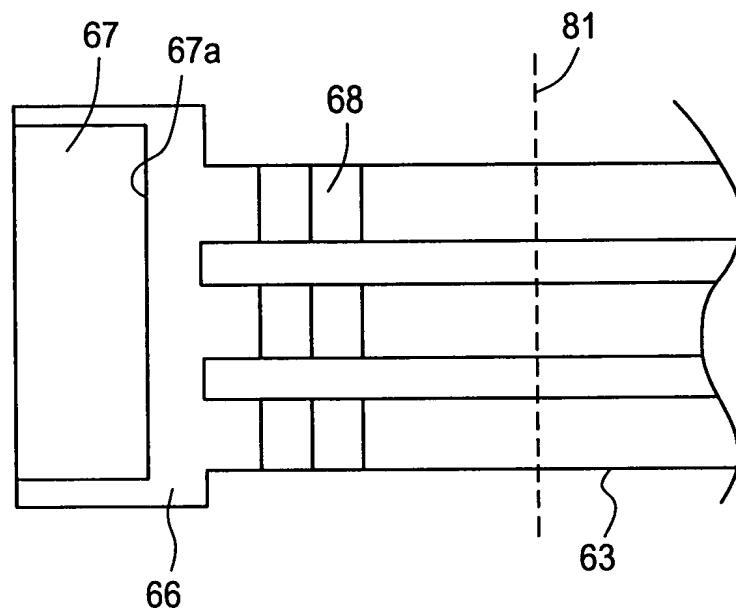
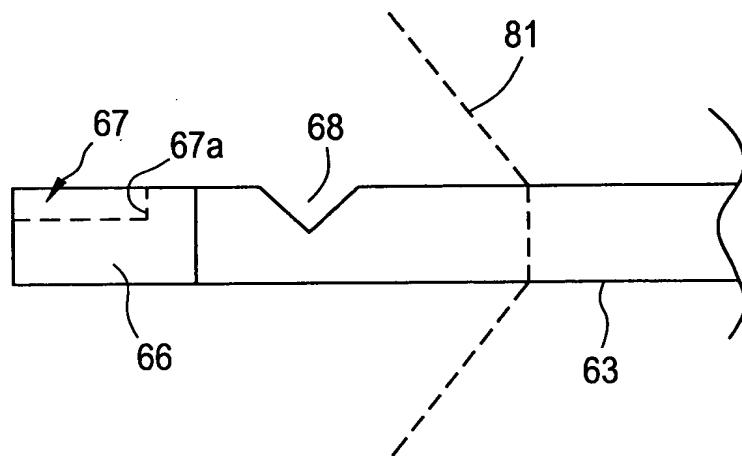


FIG. 8B



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FIG. 9A

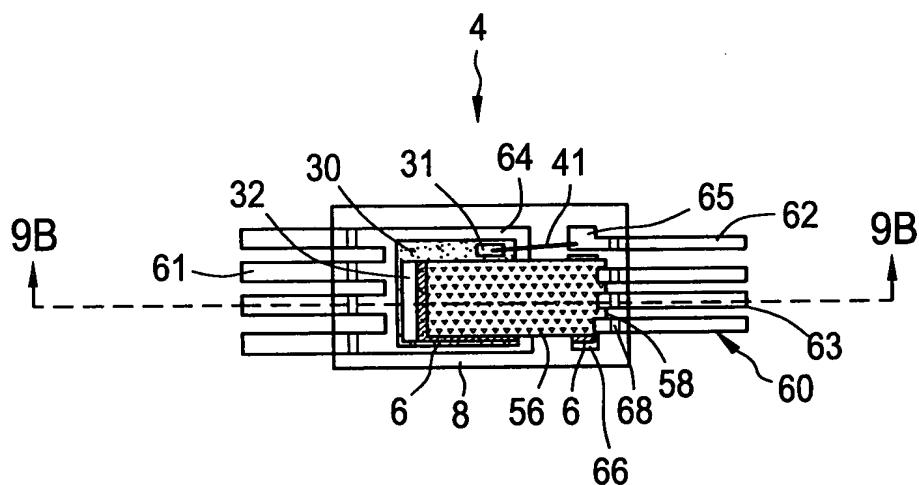
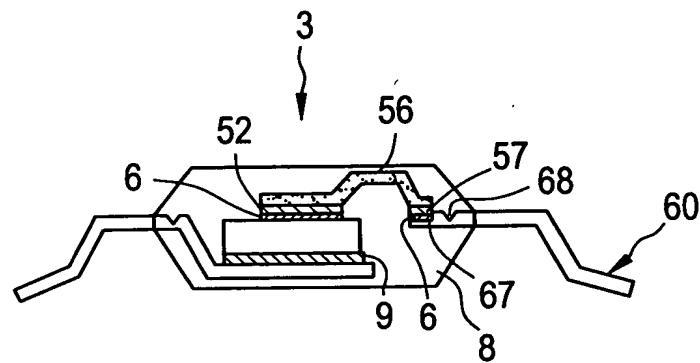


FIG. 9B



DO NOT SCALE - 1:1000000

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FIG. 10A

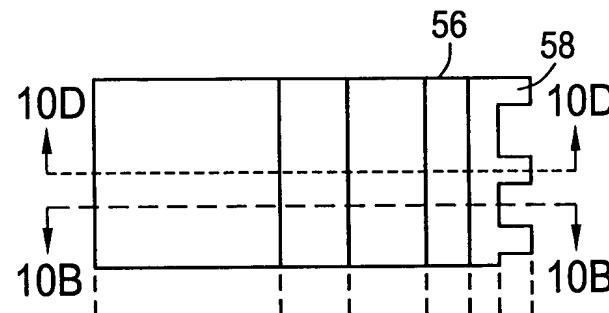


FIG. 10B

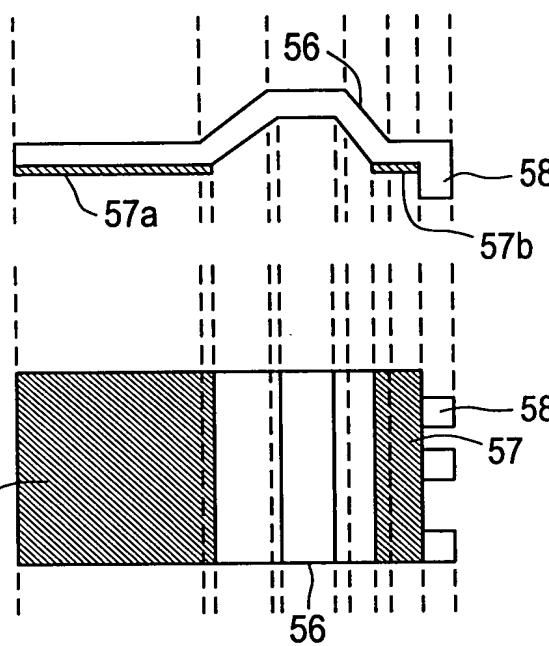


FIG. 10C

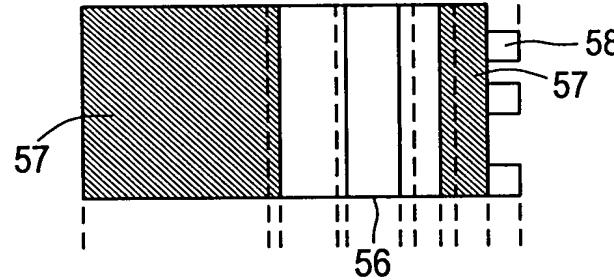


FIG. 10D

